LCD Module Product Specification

□ : APPROVAL FOR SPECIFICATION

ider

For Customer : _____ : APPROVAL FOR SAMPLE

Module No. : <u>TST350MTQI-02</u>

For Customer's Acceptance

Approved by	Comment
3	

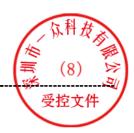
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:

Team Source Display

Presented by	Reviewed by	Organized by
Bengeberg	27.07	3 mg/2

This module uses ROHS material



				DDMADIZ
DATE	REF. PAGE	REVISED	SUMMARY	REMARK
	PARAGRAPH	No.		
	DRAWING No.			
2012-10-24		01	FIRST ISSUE	
2012-11-27	P6	02	Modify mechanical drawing	

Records of Revision

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1. Introduction

1.1 Scope of application

This specification applies to the Negative type TFT transflective dot matrix LCD module.

LCD specification: Dots 240xRGBx320.

As to basic specification of the driver IC, refer to the IC (ILI9341) specification and datasheet.

1.2 Structure:

Double display structure: TFT Module + FPC +BL 262K FULL Dithering Color3.5 inch TFT LCD size for main LCD; One bare chip with gold bump (COG) TECH;

1.3 TFT features:

Structure: TFT PANNEL+IC+FPC+BL; Transflective Type LCD 240 dot-source and 320 dot-gate outputs; White LED back light;

1.4 Applications:

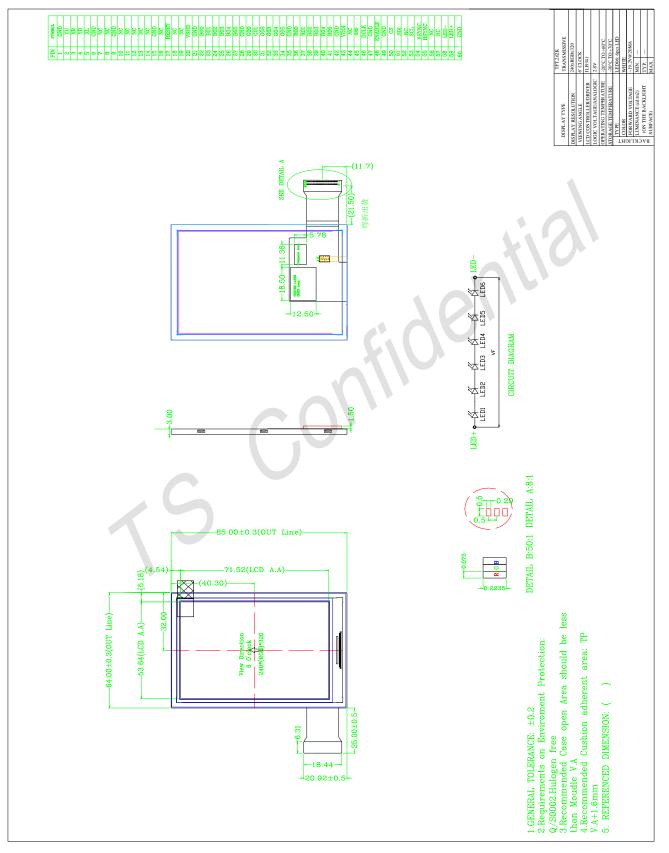
Mobile phone

PSP PDA GPS Etc...

2. General specification

ITEM	Standard value	UNIT
LCD Type	TFT Transflective	
Driver element	a-Si TFT	
Number of Dots	240*(RGB)*320	Dots
Pixel Arrangement	RGB Vertical Stripe	
Active Area	53.64x71.52	mm
Viewing Area (W*H)	/	mm
Viewing Direction	6 0' clock	
Driver IC	ILI9341	
LCM Module Size(W*H*T)	64.0x85.0x3.0MAX	mm
Approx. Weight	TBD	g
Back Light	6 White LEDS	
System interface	RGB 18 bit+SPI	
3	CON	

3. Mechanical drawing



4. ABSOLUTE MAXIMUM RATINGS

DRIVING TFT LCD PANEL

Item	Symbol	Min	Max	Unit
Supply voltage	VSHD	-0.3	4.6	V
Driver Supply voltage	VGH-VGL	-0.3	+32	V
Logic Supply voltage	VDDI	-0.3	4.6	V
Operating temperature	T _{OP}	-20	+70	°C
Storage temperature	T _{st}	-30	+80	°C

Storage temperature		1 _{ST}	-30		+80	Ĵ
5. ELECTRICAL CHAI BACKLIGHT	RACTERI	STICS	C (16		
Item	Symbol	Min	Тур	Max	Unit	REMARK
Forward Current	IF		20		mA	
Forward voltage	$V_{\scriptscriptstyle BL}$	18	19.2	21	V	With 6 LEDS
Backlight Power Consumption	W _{BL}		390	600	mW	
CIE	Х	0.240		0.300		IF=20 mA
	Y	0.240		0.300		11 20 1114
LIFE TIME			25000		HRS	

TFT LCD PANEL

Item	Symbol	Min	ТҮР	Max	Unit	REMARK
Supply voltage	VSHD	2.3	2.8	3.3	V	
Logic Supply voltage	VDDI	1.65	2.8	3.3	V	

6. Data input timing

6.1 Signal	AC Timing
------------	-----------

•			(VSHD=2.5~3.	2V,Ta=25℃)
Parameter	Description	Min	Max	Unit
tSYNCS	VSYNC/HSYNC setup time	15		ns
tSYNCH	VSYNC/HSYNC	15		ns
tENS	ENAB	15		ns
tENH	ENAB	15		ns
tPOS	Data	15		ns
tPDH	Data	15		ns
PWDH	DCLK high-level period	15		ns
PWDL	DCLK low-level period	15		ns
tCYCD	DCLK cycle time	100		ns
trgbr, trgbf	DCLK,HSYNC,VSYNC rise/fall		15	ns

Table 6.1 RGB Interface Characteristics

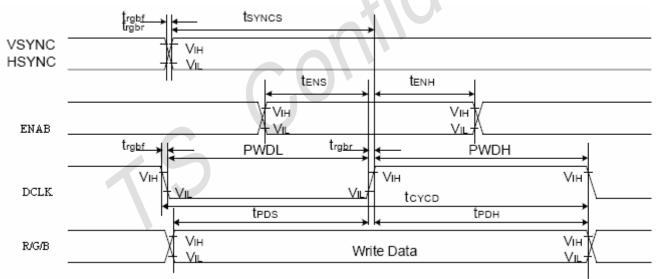


Fig.6-1 RGB Interface Timing

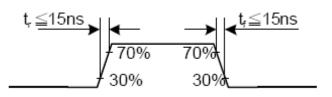


Fig.6-2 Input signal's rise and fall times

		(VSHD=2.5~3.2V,Ta=25℃)						
Parameter	Symbol	Symbol	Min	Тур	Max	Unit		
DCLK	DCLK frequency	fDCYC		5.64	10	MHz		
	DCLK period	tDCYC	100	177.15		ns		
	Horizontal	Thd		240	• •			
HSYNC	1horizontalline	Th		310				
	Horizontal blank	Thb	56	60		DCLK		
	Horizontal front porch	Thfp	2	10	16			
	Vertical display area	Tvd		320				
VSYNC	Vsync period time	Τv		328				
	Vsync blank	Tvb	2	4		Line		
	Vsync Front porch	Tvfp	2	4				

6.2 Recommend RGB Interface Timing

Tab.6-2 Recommend Input Timing (DCLK, HSYNC, VSYNC, ENAB)

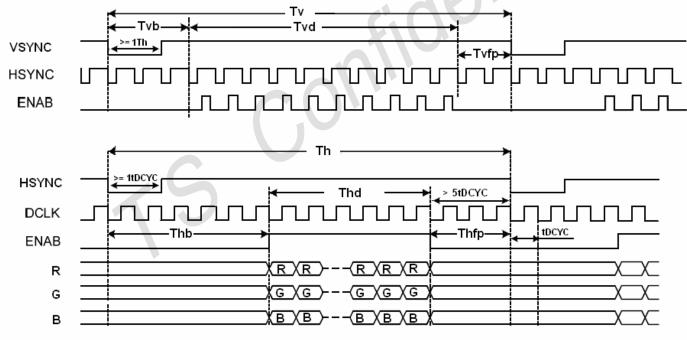
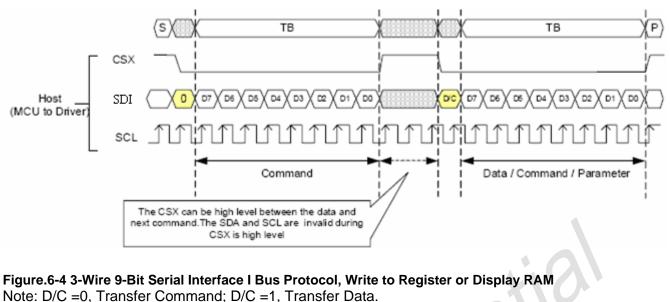


Fig.6-3 Recommend RGB Interface Timing

6.2 3-Wire 9-BIT Serial Interface

6.2.1 3-Wire 9-Bit data serial interface write mode

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6.2.2 3-Wire 9-Bit data serial interface read 1-byte mode

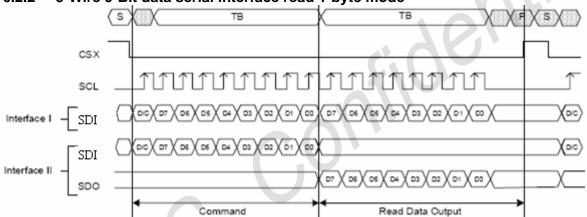
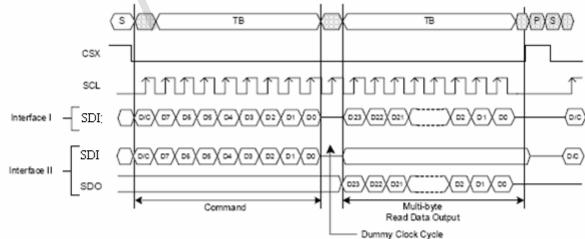
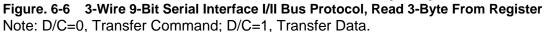


Figure. 6-5 3-Wire 9-Bit Serial Interface I/II Bus Protocol, Read 1-Byte From Register Note: D/C=0, Transfer Command; D/C=1, Transfer Data 6.2.3 3-Wire 9-Bit data serial interface read 3-byte mode





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Parameter	Symbol	Conditions	Min	Max	Unit	Remark
Serial Clock Cycle(Write)	tscycw	SCL	100		ns	Remark
SCL "H" pluse width(Write)	tshw	SCL	40		ns	
SCL "L" pluse width(Write)	tslw	SCL	40		ns	
Data setup time(Write)	tsds	SDI	30		ns	
Data hold time(Write)	tsdh	SDI	30		ns	
Serial Clock Cycle(Read)	tscycr	SCL	150		ns	
SCL "H" pluse width(Read)	tshr	SCL	60		ns	
SCL "L" pluse width(Read)	tslr	SCL	60		ns	
Access time	tacc	SDO(Read)	10		ns	
Output disable time	toh	SDO(Read)	10	50	ns	
CS "H" pluse width	tchw	CS	40		ns	
CS-SCL time	tcss	CS(write)	60	-	ns	
	tcsh	CS(write)	65		ns	

6.2.4 3-Wire 9-Bit serial interface Timing

Tab.6-3 AC Characteristics of 3-Wire 9-Bit Serial Interface

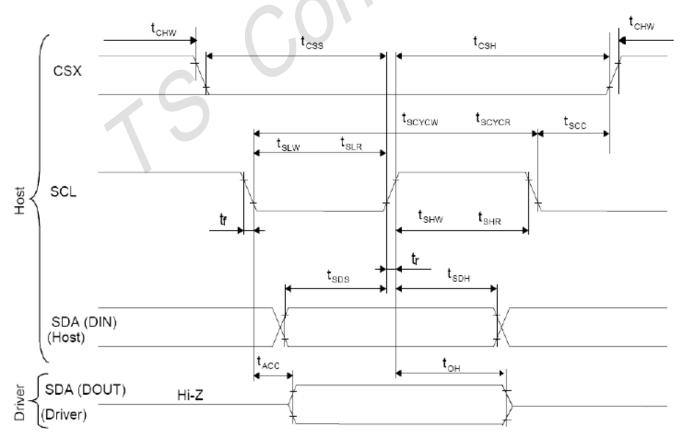


Fig.6-7 AC Characteristics of 3-Wire 9-Bit Serial Interface timing

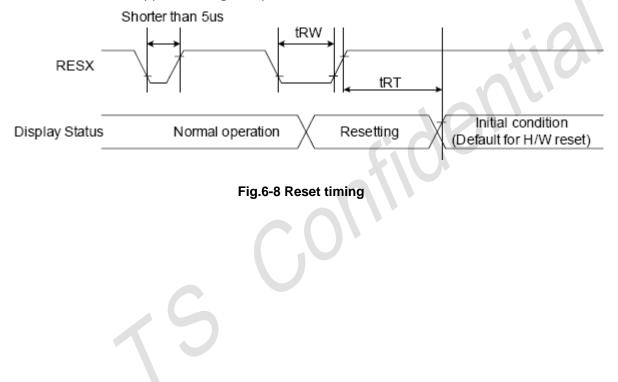
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6.3 Reset Timing

Parameter	Symbol	MIN	TYP	MAX	Unit	Remark
DEOET	tRW	10			us	
RESET	(D.T.			5	ms	note 1
	tRT			120	ms	note 2

Tab.6-4 Reset input timing

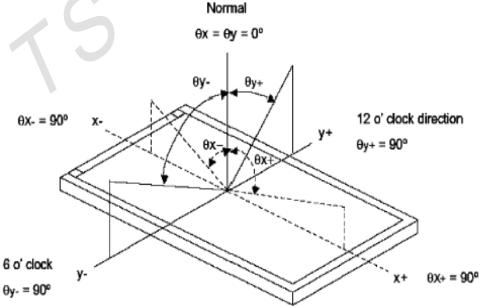
Note1: When Reset applied during Sleep In Mode. Note2: When Reset applied during Sleep Out Mode.



7. OPTI	Ta=25℃							
ITEM		SYMBOL CONDITION	CONDITIONS	SPEC	IFICAT	IONS	UNIT	NOTE
		SIMDUL	CONDITIONS	MIN.	TYP.	MAX		NOIL
Brightness		В		80	90		Cd/m^2	
Contrast Ra	tio	CR		100	150			
Response Ti	me	Tr+Tf			35		ms	
	Red	Xr			0.624			
		Yr	Viewing		0.368			All left
CIE	Green	Xg	normal angle		0.35			side data
Color		YG			0.55			are based on
coordinate	Blue	XB			0.143			TIANMA' s
coordinate		YB			0.119			product
	White	Xw			0.310		K	reference
		Yw			0.320			only
	Hor.	$\theta_{_{X+}}$			40			-
Viewing		$\theta_{_{X-}}$	Center		45	<u> </u>	Dem	
Angle	Ver.	$ heta_{_{Y+}}$	CR>=10		55		Deg.	
		$ heta_{_{Y-}}$			40			
Uniformity	Un			80	90		%	
						•	•	

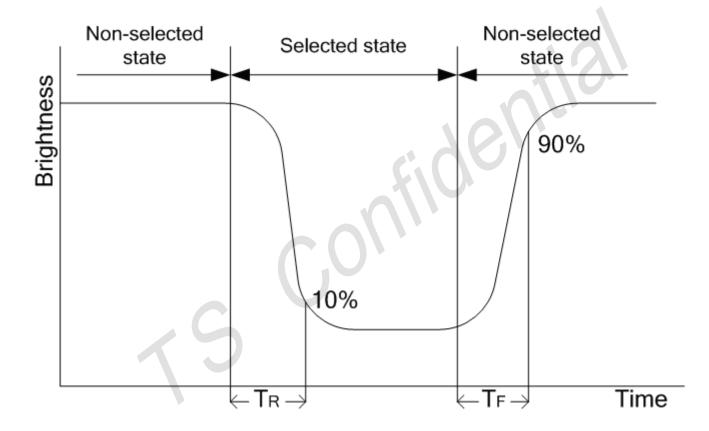
OPTICAL CHARACTERISTICS 7

Note 1 : Definition of Viewing Angle 9 x and 9 y :



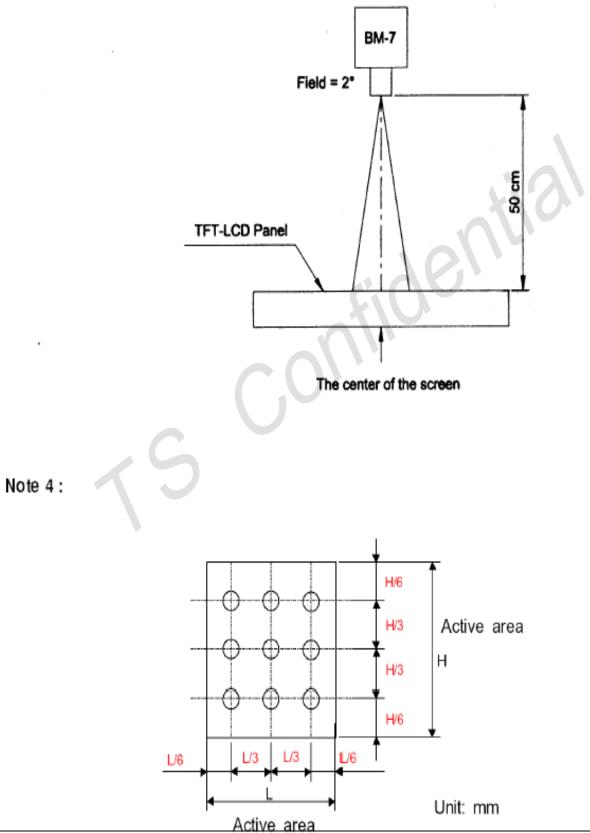
Note 2: Definition of contrast ratio CR: $CR = \frac{Brightness of non-selected dots (white)}{Brightness of selected dots (black)}$

Note 3: Definition of response time (Tr, Tr)



The brightness test equipment setup

20mA Field=2° (As measuring "black" image, field=2° is the best testing condition)



8. Interface Pin Function

	İ	. <u>Table 2: Fill assignment</u>
Pin No.	Symbol	Description
1	GND	Ground
2	YU	TP YU
3	XR	TP XR
4	YD	TP YD
5	XL	TP XL
6	GND	Ground
7	NC	NO CONNECT
8	NC	NO CONNECT
9	GND	Ground
10	NC	NO CONNECT
11	NC	NO CONNECT
12	NC	NO CONNECT
13	NC	NO CONNECT
14	NC	NO CONNECT
15	GND	Ground
16	NC	NO CONNECT
17	RESET	Reset(Low active)
18	NC	NO CONNECT
19	NC	NO CONNECT
20	VSHD	Analog Supply Voltage 2.8V
21	GND	Ground
22	B0	Blue data input(LSB)
23	B1	Blue data input
24	B2	Blue data input
25	B3	Blue data input
26	B4	Blue data input
27	B5	Blue data input(MSB)
28	GND	Ground
29	GO	Green data input(LSB)
30	G1	Green data input
31	G2	Green data input
32	G3	Green data input
33	G4	Green data input
34	G5	Green data input(MSB)
35	GND	Green data input

. Table 2: Pin assignment

36	RO	Ded data input/LCD)
		Red data input(LSB)
37	R1	Green data input
38	R2	Green data input
39	R3	Green data input
40	R4	Green data input
41	R5	Red data input(MSB)
42	GND	Ground
43	VDDI	Logic Supply Voltage 2.8V
44	NC	NO CONNECT
45	GND	Ground
46	DCLK	Pixel clock signal in RGB mode
47	GND	Ground
48	ENABLE	Data enable
49	GND	Ground
50	CS	Chip select input(Low enable)
51	SDI	Serial data input
52	NC	NO CONNECT
53	SCL	Serial interface clock input
54	VSYNC	Vertical SYNC input
55	HSYNC	Horizontal sync in RGB mode
56	NC	NO CONNECT
57	NC	NO CONNECT
58	LED-	Power supply for LED(Low voltage)
59	LED+	Power supply for LED(High voltage)
60	GND	Ground

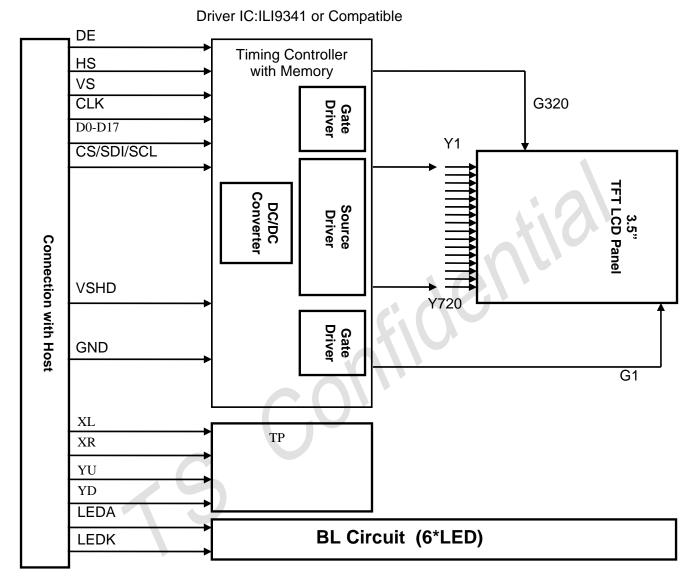
Note:

1. The PIN connect is :AXK6F60347YG.

9. BLOCK DIAGRAM

CL

IAUNAM

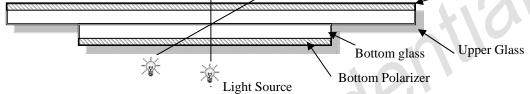


10.LCM Quality Criteria

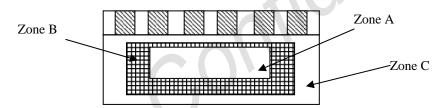
10.1 VISUAL & FUNCTION INSPECTION STANDARD

10.1.1 Inspection conditions

Inspection performed under the following conditions is recommended. Temperature : 25 ± 5 °C Humidity : $65\%\pm10\%$ RH Viewing Angle : Normal viewing Angle. Illumination: Single fluorescent lamp (300 to 700Lux) Viewing distance: 30-50cm Upper Polarizer



10.1.2 Definition



Zone A : Effective Viewing Area(Character or Digit can be seen)

Zone B : Viewing Area except Zone A

Zone C : Outside (Zone A+Zone B) which can not be seen after assembly by customer .) Note:

As a general rule ,visual defects in Zone C can be ignored when it doesn't effect product function $% \left(\mathcal{L}^{2}\right) =\left(\mathcal{L}^{2}\right) \left(\mathcal{L}^{2$

or appearance after assembly by customer.

10.1.3 Sampling Plan

According to GB/T 2828-2003 ; , normal inspection, Class II AQL:

Major defect	Minor defect					
0.65	1.5					

LCD: Liquid Crystal Display , TP: Touch Panel , LCM: Liquid Crystal Module

No	Items to be	Criteria	Classification of
	inspected		defects

1	Functional defects	 No display, Open or miss line Display abnormally, Short Backlight no lighting, abnormal lighting. TP no function 	Major
2	Missing	Missing component	
3	Outline dimension	Overall outline dimension beyond the drawing is not allowed	
4	Color tone	Color unevenness, refer to limited sample	
5	Soldering	Good soldering , Peeling off is not	Minor
	appearance allowed.		
6	6 LCD/Polarizer/TP Black/White spot/line, scratch, crack, etc.		

10.1.4 Criteria (Visual)

Number	Items	Criteria(mm)				
1.0 LCD Crack/Broken NOTE:	(1) The edge of LCD broken					
X: Length Y: Width		X Y Z				
Z: Height L: Length of	C U	$ \begin{array}{ c c c } \leqslant 3.0 \text{mm} & \stackrel{<}{}^{\text{Inner border}} \\ 1 \text{ ine of the seal} & \leqslant T \end{array} $				
ITO, T: Height of LCD	(2)LCD corner broken					
		XYZ $\leq 3. 0$ mm $\leq L$ $\leq T$				

(3) LCD crack	Crack Not allowed

Number	Items		Cr	iteria (mm)		
2.0	Spot defect	① light dot (LCD dent, stain)	spot , light	dot, pinhole,		
	Y	Zone	Ac	ceptable Qty	7	
		Size (mm)	А	В	С	
	X	Ф ≼0. 10	Ignor	e		
	$\Phi = (X+Y)/2$	0. 10< Φ ≤0. 15	3(distance	≥ 10 mm)	Ignore	
	- (A·1)/2	0. 15< Φ ≤0. 2	1		1ghore	
		0. 2<Φ	0			
		②Dim spot (LCD/T	P/Polarizer di	n dot, light	leakage, dar	k spot)
		Zone	Ac	ceptable Qty	7	
		Size (mm)	А	В	С	
		Φ≤0.1	Ignor	e		
		0. 1<Φ≤0. 2	2(distance	≥ 10 mm)	Ignore	
		0. $2 < \Phi \le 0.3$	1		1 ghoi e	
		Φ>0. 3	0			
		③ Polarizer acci	dented spot			
		Zone	Ac	ceptable Qt	у	
		Size (mm) A B Φ≤0.2 Ignore		В	С	
		0. 2<Φ≤0. 5	2(distanc	$e \ge 10$ mm)	Ignore	
		Φ>0.5	0		1	

$ \begin{array}{ c c c c c } \hline & (LCD/TP \\ /Polarizer \\ black/white \\ line, \\ scratch, \\ stain) \end{array} \hline & Width(mm) & Length(mm) & Acceptable Qty \\ \hline A & B & C \\ \hline & \Phi \leqslant 0.03 & Ignore & Ignore \\ \hline & 0.03 \langle W \leqslant 0.05 & L \leqslant 3.0 & N \leqslant 2 & Ignore \\ \hline & 0.03 \langle W \leqslant 0.05 & L \leqslant 2.0 & N \leqslant 2 & Ignore \\ \hline & 0.05 \langle W \leqslant 0.08 & L \leqslant 2.0 & N \leqslant 2 & Ignore \\ \hline & 0.05 \langle W \leqslant 0.08 & L \leqslant 2.0 & N \leqslant 2 & Ignore \\ \hline & 0.08 \langle W & Define as spot defect \\ \hline & & & & & & \\ \hline & & & & & & & \\ \hline & & & &$		Line defect							_		
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$			W: 1+1 ()	N N		Ac	ceptable	e Qty			
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$		black/white	width(mm))	Length(mm)	А	В	С			
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$			Ф≤0.03	1	Ignore	Ign	lore				
Image: Constraint of the system of the s			0.03<₩≤0.	05	L≤3.0	N≤	≤2	Ignore			
3.0 Polarizer Bubble $Zone$ Acceptable Qty Ignore 3.0 Polarizer Bubble $\boxed{2 \text{ Ignore}}$ $0.2 < \Phi \leq 0.2$ $0.2 < \Phi \leq 0.4$ $0.4 < 0.6$ 0 1 Ignore $0.6 < \Phi$ 4.0 SMTAccording to IPC-A-610C class II standard . Function defect and missing part are major defect , the others are minor defect. 4.0 SMTAccording to IPC-A-610C class II standard . Function defect and missing part are major defect , the others are minor defect. 4.0 SMTAccording to IPC-A-610C class II standard . Function defect and missing part are major defect , the others are minor defect. 4.0 SMTAccording to IPC-A-610C class II standard . Function defect and missing part are major defect , the others are minor defect. 4.0 SMTAcceptable Qty Ignore $0.1 < \Phi \leq 0.1$ $0.3 < \Phi$ 0 $0.1 < \Phi \leq 0.2$ 2 $0.3 < 1$ 0 IgnoreAssemblybeyond the edge of backlight ≤ 0.15 mm			0.05<₩≤0.	08	L≤2.0	N≤	≤2				
3.0Polarizer BubbleSize (mm)ABC $\Phi \le 0.2$ Ignore 0.2< $\Phi \le 0.4$ 2(distance $\ge 10 \text{nm}$) 0.4< $\Phi \le 0.6$ Ignore $0.4 < \Phi \le 0.6$ 1Ignore $0.6 < \Phi$ 0Ignore 4.0 SMTAccording to IPC-A-610C class II standard . Function defect and missing part are major defect , the others are minor defect. 4.0 SMTAccording to IPC-A-610C class II standard . Function defect and missing part are major defect , the others are minor defect. 4.0 SMTAccording to IPC-A-610C class II standard . Function defect and missing part are major defect , the others are minor defect. 4.0 SMTAccording to IPC-A-610C class II standard . Function defect and missing part are major defect . 4.0 SMTAccording to IPC-A-610C class II standard . Function defect and missing part are major defect . 4.0 SMTAccording to IPC-A-610C class II standard . Function defect and missing part are major defect . 4.0 SMTAccording to IPC-A-610C class II standard . Function defect and missing part are major defect . 4.0 SMTAccording to IPC-A-610C class II standard . Function defect and missing part are major defect . 4.0 SMTAccording to IPC-A-610C class II standard . Function defect . 4.0 SMTAccording to IPC-A-610C class II standard . Function defect . 4.0 SMTAccording to IPC-A-610C class II standard . Function defect . 4.0 SMTAccording to IPC-A-610C class II standard . Function defect . 4.0 According to IPC-A-610C clas			0.08 <w< td=""><td></td><td>Defi</td><td>ne as sp</td><td>oot defe</td><td>ct</td><td></td><td></td></w<>		Defi	ne as sp	oot defe	ct			
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3.0Polarizer Bubble \square			Zc	one	A	cceptabl	e Qty				
3.0Bubble $\Phi \leq 0.2$ Ignore 0.2< $\Phi \leq 0.4$ Ignore0.2< $\Phi \leq 0.4$ 2(distance ≥ 10 mm)Ignore0.4< $\Phi \leq 0.6$ 10.6< Φ 04.0SMTAccording to IPC-A-610C class II standard . Function defect and missing part are major defect , the others are minor defect.TP bubble/ accidented spotTP bubble/ accidented spotMathematical Size $\Phi \leq 0.1$ Ignore $\Phi \leq 0.1$ Ignore $0.1<\Phi \leq 0.2$ $0.2< \Phi \leq 0.3$ 1 $0.3< \Phi$ 0Assemblybeyond the edge of backlight ≤ 0.15 mm			Size (mm)		А	A B C		0			
4.0SMT $0.2 < \Phi \le 0.4$ $0.4 < \Phi \le 0.6$ 0 1 1 gnore4.0SMTAccording to IPC-A-610C class II standard . Function defect and missing part are major defect , the others are minor defect.TP bubble/ accidented spotSize Φ (mm)Acceptable Qty $\Phi \le 0.1$ Ignore $0.1 < \Phi \le 0.2$ 2 $0.2 < \Phi \le 0.3$ 1 $0.3 < \Phi$ 0 Assemblybeyond the edge of backlight ≤ 0.15 mm	3.0		Φ≤0.2		Ignore						
$0.4 < \Phi \le 0.6$ 1 $0.6 < \Phi$ 0 $0.6 < \Phi$ 0 4.0 SMTAccording to IPC-A-610C class II standard . Function defect and missing part are major defect , the others are minor defect. 1.0 SMT $According to IPC-A-610C class II standard . Function defect and missing part are major defect , the others are minor defect.1.0TP bubble/accidented spotAcceptable QtyA B C0.1 < \Phi \le 0.10.1 < \Phi \le 0.20.2 20.2 < \Phi \le 0.310.3 < \PhiIgnore1.0Assemblybeyond the edge of backlight \le 0.15mm$	5.0	Dubbit	0. 2<Φ≤0. 4		2(distance	$e \ge 10$ mm)	Т	an o n o			
4.0SMTAccording to IPC-A-610C class II standard . Function defect and missing part are major defect , the others are minor defect.TP bubble/ accidented spotTP bubble/ Size Φ (mm)Acceptable Qty A B 0.1 Ignore 0.1<4 \$<0.2			0.4<Φ≤0.6		1			gliore			
4.0SM1part are major defect , the others are minor defect.TP bubble/ accidented spotSize Φ (mm)Acceptable Qty A B C $\Phi \leq 0.1$ Ignore $0.1 < \Phi \leq 0.2$ 2 $0.2 < \Phi \leq 0.3$ 1 $0.3 < \Phi$ 0Assemblybeyond the edge of backlight ≤ 0.15 mm			0.6<Φ	0							
4.0SM1part are major defect , the others are minor defect.TP bubble/ accidented spotSize Φ (mm)Acceptable Qty A B C $\Phi \leq 0.1$ Ignore $0.1 < \Phi \leq 0.2$ 2 $0.2 < \Phi \leq 0.3$ 1 $0.3 < \Phi$ 0Assemblybeyond the edge of backlight ≤ 0.15 mm											
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deflection beyond the edge of backlight ≤ 0.15 mm			Assembly	ssembly							
			deflection		beyond	the eag	e or bac	skiignt ≥	0.1000		

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5.0	TP Related						() 1規律性
		Newton Ring	Newton Rin NG Newton Rin OK				2.排玩業生
				C	96	2	
		TP corner broken X: length Y: width Z: height	X X≤3.0mm * Circuitry	Y Y≤3.0mm broken is	Z Z <lc thickne</lc 		x
			allowed.				
		TP edge				\neg	
		broken	X	Y	Z		X
		X: length Y: width	X≪6.0mm	Y≤2.0mm	Z <lcd thickne</lcd 		
		Z: height	* Circuitr	v broken is		55	
		2	allowed.	,			
Criteria (f	unctional i	tems)	1			I	
	Number		Items				Criteria (mm)
	1			No display			Not allowed
2			Missing segment				Not allowed
3			S	hort			Not allowed
	4			no lightin	ng		Not allowed
	5		TP no	function			Not allowed

10.2 RELIABILITY TEST

NO	ITEM	CONDTTION	STANDARD
1	High Temp. Storage	70°C, 240 hours	1. Functional test

2	Low Temp. Storage	-30℃, 240 hours	
3	High Temp. Operation	60°C, 240 hours	
4	Low Temp. Operation	-20°C, 240 hours	
5	High temperature and high Humidity storage	40°C,90%RH ,240 hours	
6	Thermal and cold shock	Static state, -30°C (30 Min) ~70°C (30 Min) ~ -30°C (30Min), packaging, 20 cycles	
7	Vibration test	Packaging, Frequency : 10-55Hz Amplitude : 1.0mm, Each direction on X,Y axe 0.5 houre, circle 2 hours	 Function test is OK. No glass crack, chipped glass, end seal loose and fall, epoxy frame crack and so on. No structure loose and fall.
8	Dropping test	Pack products into the carton box. Drop it from 80cm height to ground. Once for each side of the carton	

NOTE:

10.2.1 The reliability items will be fully performed in new sample qualification,

10.2.2 The reliability status will be tested as monitor during mass production. Individual reliability test shall be

performed by lot , Moreover, the individual reliability item shall be decided according to reliability plan.

- 10.2.3 All samples are inspected after keeping in the room with normal temperature and humidity for 2 hours or above.
- 10.2.4 Vibration test: It is not necessary to test for those products without assembly frame , back light , PCB and so on.

10.2.5 Dropping test : It is necessary for affirming new package.

10.2.6 For the high temperature and high humidity test, pure water of over 10 M $\!\Omega.\,cm$ should be used.

 $10.\,2.\,7$ Each test item applies for test LCM only once .Then tested LCM cannot be used again in any other test item.

10.2.8 The quantity of LCM examination for each test item is 5pcs to 10pcs.

10.3 Safety instructions

 $10.\,3.\,1$ If the LCD panel breaks, be careful not to get any liquid crystal substance in your mouth.

10.3.2 If the liquid crystal substance touches your skin or clothes, please wash it off immediately by using soap and water.

10.4 Handling Precautions

10.4.1 Avoid static electricity damaging the LSI.

 $10.\,4.\,2$ Do not remove the panel or frame from the module .

 $10.\,4.\,3$ The polarizing plate of the display is very fragile . So, please handle it very carefully.

10.4.4 Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of the plate.

10.4.5 The color tone of display and background of LCM has the possibility to be changed in the storage temperature range.

10.4.6 Pay attention to the working environment, as the element may be destroyed by static electricity.

--Be sure to ground human body and electric appliance during work.

--Avoid working in a dry environment to minimize the generations of static electricity.

--Static electricity may be generated when the protective film is fast peeled off.

10.4.7 When soldering the terminal of LCM, make certain the AC power source of soldering iron does not leak.

10.4.8 If the display surface becomes contaminated ,breathe on the surface and gently wipe it with a soft-dry- clean cloth .If it is heavily contaminated ,moisten cloth with the following solvent(ex:Ethyl alcohol).Solvents other than those above-mentioned may damage the polarizer(Especially ,do not use them .ex: Warter / Ketone)

10.5 Operation instructions

- 10.5.1 It is recommended to drive the LCD within the specified voltage limits, try to adjust the operating voltage for the optimal contrast, the color and contrast of LCD panel will varies at different temperature.
- 10.5.2 Response time is greatly delayed at low operating temperature range. However, this does not mean the LCD will be out of the order, It will recover when it returns to the specified temperature range.
- 10.5.3 If the display area is pushed hard during operation, the display will become abnormal.
- 10.5.4 Do not operate the LCD at the environments over the specified conditions, this may cause damage on the LCD and shorten the lifetime.

10.6 Storage instructions:

10.6.1 Store LCDs in a sealed polyethylene bag.

10.6.2 Store LCDs in a dark place, Do not expose to sunlight or fluorescent light. Keep the temperature between 0°Cand 35°C.

10.6.3 Avoid the polarizer touch any other object, (It is recommended to store them in the container in which they were shipped.)

10.7 Limited Warranty

- 10.7.1 will replace or repair any of its LCD modules, which are found to be defective, when inspected in accordance with LCM acceptance standards (copies available upon request) for a period of 12 months from ink- print date on product
- 10.7.2 Any defects must be returned to within 60 days since ship-out. Confirmation of such date shall be based on freight documents. The warranty liability of wasam limited to repair and/or replacement on defects above (7.1,7.2)
- 10.7.3 No warranty can be granted if the precautions stated above have been disregarded. The typical samples are as below:
 - -- LCD glass crack/break
 - --PCB outlet is damaged or modified.
 - --PCB conductors damaged.
 - --Circuit modified with by grinding, engraving or painting varnish.

--FPC crack

10.7.4 Modules must be returned with sufficient description of the failures of defects. Any

connectors or cable installed by the customer must be removed completely without damaging

the PCB outlet, conductors and terminals. Modules must be packed with the container in which they were shipped.



11. Packing method

